



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Vernon M. Williams

Serial No.: 09/652,503

Filed: August 31, 2000

For: TRANSFER MOLDING AND
UNDERFILLING METHOD AND
APPARATUS

Confirmation No.: 3679

Examiner: W. Brewster

Group Art Unit: 2823

Attorney Docket No.: 2269-4303US
(99-0584.00/US)

Notice of Allowance Mailed:

December 3, 2003

NOTICE OF EXPRESS MAILING

Express Mail Mailing Label Number: EV326918080US

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Person making Deposit: Christopher Haughton

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the Title appear on page 3 of this paper.

Serial No. 09/652,503

Amendments to the Specification begin on page 4 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 7 of this paper.

Remarks begin on page 16 of this paper.

IN THE TITLE:

The title has been amended herein. Pursuant to 37 C.F.R. §§ 1.121 and 1.125 (as amended to date), please enter the title as amended.

**TRANSFER MOLDING AND UNDERFILLING METHOD AND APPARATUS
INCLUDING ORIENTING THE ACTIVE SURFACE OF A
SEMICONDUCTOR SUBSTRATE ~~CHIP~~ SUBSTANTIALLY VERTICALLY**